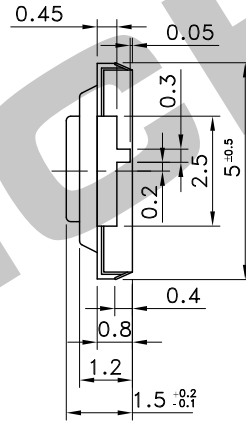
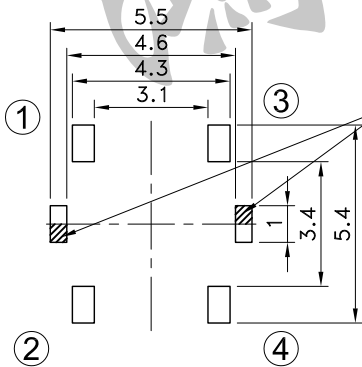


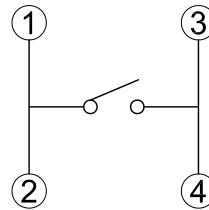
P.C.B TERMINAL POSITION



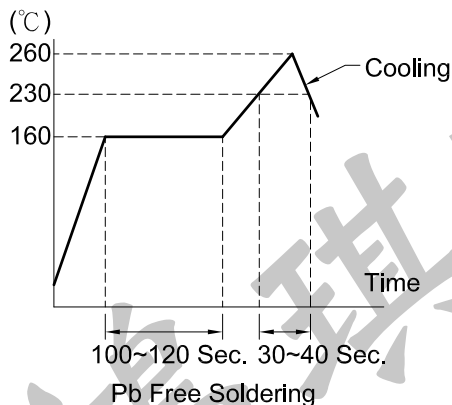
CIRCUIT ARRANGEMENT



GROUND PIN:
The thickness of cream solder:150~200 μ
We recommend to connect the GND land shown in the switch spec. with the GND of your P.C.B for withstanding electric-static discharge.



REFLOW SOLDERING CONDITIONS



SPECIFICATIONS

- 1. Rating : DC 15V 20mA
- 2. Contact Resistance : 50mΩ Max.
- 3. Insulation Resistance : 50MΩ Min. at DC 100V
- 4. Dielectric Strength : AC 250V For 1 Minute
- 5. Operating Force : 350±100gf
- 6. Stroke : 0.25^{+0.1}_{-0.2} mm
- 7. Life : 200,000 Cycles
- 8. Taping : 5,000 Pcs/Reel
- 9. Reflow Soldering Profile : According Reflow Profile Max. 2 Times

| | | | | | | | |
|------------|--|-------------------------------|--|---|--|-------------------|--|
| REVISION: | | DATE: | | REVISION: | | DATE: | |
| UNIT:mm | | THIRD ANGLE PROJECTION METHOD | | TOL. UNLESS OTHERWISE STATED:±0.3 | | CODE NO.:HCH-2125 | |
| ISSUED | | CONFIRMED | | PART NO. | | | |
| John | | Elvis | | HCH [®] HORNG CHIH | | STS-05-C | |
| 2017.10.02 | | 2017.10.02 | | ISO9001 Certified ISO14001 Certified 鴻琪股份有限公司 | | | |